

S101_V3



- Intel 12th generation Alder Lake-S series
- Intel 13th generation Raptor Lake-s series,
- Onboard memory, 2 x DDR4 SO-DIMM, up to 64GB
- EFI BIOS
- 6 x LAN ports 2.5Gbs intel i226
- 4 x SFP ports 10Gbs intel x710-BM2
- 1 x Micro SIM card slot & modem 3g,4g,5g
- ATX 24+8 Pin power supply, above 300W



The actual appearance is subject to the final configuration.

Specifications

MODEL	S101_V3		
Supported OS	Windows 10 / Windows 11 / Linux		
CPU	Model	Intel 12th generation Alder Lake-S series/13th generation Raptor Lake-s series, LGA1700, TDP 65W	
RAM	SO-DIMM	2 x DDR4 SO-DIMM, up to 64GB	
Storage Devices	SATA	4 x SATA3.0 interface (H610 does not support RAID; H670/Q670 supports RAID0/1/5/10)	
	M.2	1 x M.2 M-Key 2280 (NVMe PCIe 3.0_x4) storage interface (NVMe is not supported when the H610 chip is used)	
	CF Card	1 x CF card interface (optional, the default is SATA 3.0, when using a CF card, one SATA3.0 is required)	
I/O INTERFACE	Ethernet	1 x RJ45 Console	6 x LAN ports (i226; LAN1-2, LAN3-4 support ByPASS)
	SFP	2 or 4 x SFP+ 10G (Intel XL710-BM2)	
	USB	2 x USB 3.2	
	Video & Audio	1 x HDMI2.0 interface, support 4096x2160@60Hz	1 x VGA port
	Other	1 x Power Led, 1 x HDD Led, 1 x Reset Switch, 1 x Power Switch	
	Power supply	ATX 24+8 Pin power supply, above 300W	
Internal Motherboard Expansion Functions	TPM2.0	TPM2.0 is optional, there is no default	
	USB	1 x USB2.0 2x5 Pin, pitch 2.54mm	1 x USB3.2 2x10 Pin, pitch 2.0mm
	M.2	1 x M.2 E-Key (PCIe3.0/2.0 protocol, support WIFI/BT module)	
		1 x M.2 B-Key (USB2.0/USB3.0 protocol, support 4G/5G module)	
	Sim Card	1 x Micro SIM card slot	
	COM	1 x COM header, 2x5Pin, pitch 2.54mm	
	PCIe	1 x PCIe_8X (PCIe5.0_x8 protocol), H610 chip does not support	
Other	1 x 4Pin intelligent temperature control CPU fan, 2 system fans		
Environment	Operating Temperature	-20 ~ 60 °C	
	Storage Temperature	-40 ~ 85 °C	
	Relative Humidity	5 to 90%	

Physical Characteristics	Material	Masteel
	Dimensions	486(L) x 411(W) x 45(H)mm +/- 0.2mm (with mounting ear size)
	Net Weight	4.5 Kg with sigle Power Supply, 6.5 Kg with dual Power Supply
Regulation	EMC	FCC, CE, RoHS

Ordering Information

SO-DIMM DDR4	M.2 M-Key 2280	SATA 3.0	CF Card	RJ45	LAN Ports	SFP	USB 3.2	VGA	HDMI
2	1	4	1	1	6	4	2	1	1
USB 2.0 2x5 Pin	USB 3.2 2x10 Pin	M.2 E-Key	M.2 B-Key	COM 2x5 Pin	TMP	Internal SIM Card Slot	Power Supply		
1	1	1	1	1	Optional	1	ATX 24+8 Pin power supply, above 300W		

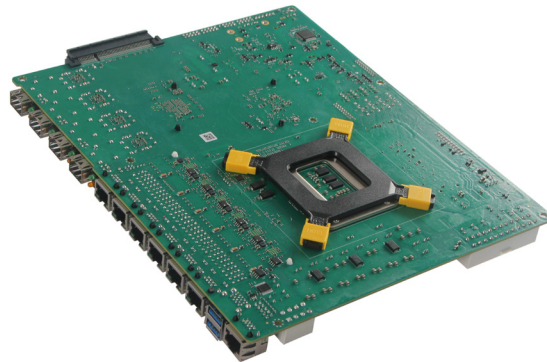
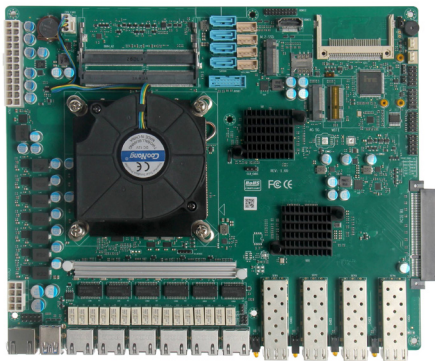
Processors Info & Available List

CPU	Total Cores	Total Threads	Max Turbo Frequency	Processor Base Frequency	Cache	Bus Speed	TDP	Memory Types
Intel® Core™ i3-12100F	4	8	4.30 GHz	3.30 GHz	12 MB Intel® Smart Cache	-	58 W	DDR4-3200
Intel® Core™ i5-12400F	6	12	4.40 GHz	2.50 GHz	18 MB Intel® Smart Cache	-	65 W	DDR4-3200
Intel® Core™ i7-12700F	12	20	4.90 GHz	1.60 GHz / 2.1 GHz	25 MB Intel® Smart Cache	-	65 W	DDR4-3200
Intel® Core™ i9-12900KF	16	24	5.20 GHz	3.20 GHz / 2.40 GHz	30 MB Intel® Smart Cache	-	125 W	DDR4-3200
Intel® Core™ i3-13100F	4	8	4.50 GHz	3.40 GHz	12 MB Intel® Smart Cache	-	58 W	DDR4-3200
Intel® Core™ i5-13400F	10	16	4.60 GHz	2.50 GHz / 1.80 GHz	20 MB Intel® Smart Cache	-	65 W	DDR4-3200
Intel® Core™ i7-13700F	16	24	5.20 GHz	2.10 GHz / 1.50 GHz	30 MB Intel® Smart Cache	-	65 W	DDR4-3200
Intel® Core™ i9-13900KF	24	32	5.40 GHz	3.00 GHz / 2.20 GHz	36 MB Intel® Smart Cache	-	125 W	DDR4-3200

Packing List

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S101_v3	1

Onboard Intel 12th generation Alder Lake-S series / 13th generation Raptor Lake-s series Specifications



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MODEL	Intel 12th generation Alder Lake-S series/13th generation Raptor Lake-s series processors		
Supported OS	Windows 10 / Windows 11 / Linux		
CPU	12th generation Alder Lake-S	Intel® Core™ i3-12100F	Intel® Core™ i5-12400F
		Intel® Core™ i7-12700F	Intel® Core™ i9-12900KF
	13th generation Raptor Lake-S	Intel® Core™ i3-13100F	Intel® Core™ i5-13400F
		Intel® Core™ i7-13700F	Intel® Core™ i9-13900KF
RAM	SO-DIMM	2 x DDR4 SO-DIMM, up to 64GB	
Storage Devices	M.2	1 x M.2 M-Key 2280 (NVMe PCIe 3.0_x4) storage interface (NVMe is not supported when the H610 chip is used)	
	CF	1 x CF card interface (optional, the default is SATA 3.0, when using a CF card, one SATA3.0 is required)	
	SATA	4 x SATA3.0 interface (H610 does not support RAID; H670/Q670 supports RAID0/1/5/10)	
Board Edge I/O Interface	Ethernet	1 x RJ45 CONSOLE	6 x LAN ports (i226; LAN1-2, LAN3-4 support ByPASS)
	USB	2 x USB 3.2	
	SFP	2 or 4 x SFP 10G (Intel XL710-BM2)	
	Video & Audio	1 x HDMI2.0 interface, support 4096x2160@60Hz	
	Power supply	ATX 24+8 Pin power supply, above 300W	
Inboard Expansion Functions	TPM2.0	TPM2.0 is optional, there is no default	
	M.2	1 x M.2 E-Key (PCIe3.0/2.0 protocol, support WIFI/BT module)	
		1 x M.2 B-Key (USB2.0/USB3.0 protocol, support 4G/5G module)	
	USB	1 x USB2.0 2x5Pin, pitch 2.54mm	1 x USB3.2 2x10Pin, pitch 2.0mm
	PCIe	1 x PCIe_8X (PCIe5.0_x8 protocol), H610 chip does not support	
	COM	1 x COM header, 2x5Pin, pitch 2.54mm	
Other	1 x 4Pin intelligent temperature control CPU fan, 2 system fans		
Environment	Operating Temperature	-20 ~ 60 °C	
	Storage Temperature	-40 ~ 85 °C	
	Relative Humidity	0% ~ 90% relative humidity, non-condensing	
Characteristics	Dimensions	255(L) x 210(W) mm	
	Weight	500g	
Regulation	EMC	FCC, CE, RoHS	

All products and company name listed are trademarks or trade names of their respective companies.

